

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 2000182691
PUBLICATION DATE : 30-06-00

APPLICATION DATE : 17-12-98
APPLICATION NUMBER : 10358500

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INT.CL. : H01R 11/01 C09J 9/02 C09J 11/06
C09J 11/08 G02F 1/1345 H01B 1/20
H01B 5/16 H05K 1/14

TITLE : CIRCUIT CONNECTING MEMBER AND
CONNECTION METHOD USING
THEREWITH



ABSTRACT : PROBLEM TO BE SOLVED: To enable intensively direct heating at high speed with no loss of heat energy and with high heating efficiency by connecting a circuit with a member containing a specific amount of conductive fine particles in an insulative binder and containing a specific amount of a substance of a specific infrared absorption wavelength band region.

SOLUTION: In this connection method, 1 to 50 wt.% of a substance with 1 to 20 μm of an infrared absorption wavelength band region, preferably 20 to 50 wt.%, is contained in a binder 2 containing a conductive material 1<25 vol.%. As this conductive material, a fine particle of a 1 to 15 μm diameter of Au, Ag, Pt, Cu, W, Sb, Sn, solder or carbon, etc., is preferable. The binder 2 shows thermosetting property; an epoxy adhesive having adhesiveness is preferable. An infrared absorption substance 3 is preferably a blackbody substance of a 3 μm average diameter such as aniline black or iron oxide. This connecting member is disposed between electrodes and is radiated with an infrared as being pressurized to be connected to both electrodes effectively and with no connection to other electrodes, thus conductivity is imparted in the pressurized direction.

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